AMENDMENTS TO AND LISTING OF CLAIMS

1. (Canceled)

2. (Withdrawn) The flexible electrical circuit of claim 1 wherein the slots are generally parallel to the longitudinal axis of the conductive traces

3. (Canceled)

4. (Withdrawn) The flexible electrical circuit of claim 1 wherein the slots extend through the dielectric layer.

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Original) An integrated lead flexure, including:

a base layer;

a plurality of elongated electrical traces on the base layer;

a dielectric coverlay over at least portions of the traces; and

slots in at least portions of the coverlay oriented non-parallel to a longitudinal axis of the traces.

12. (Withdrawn) The integrated lead flexure of claim 11 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.

13. (Original) The integrated lead flexure of claim 11 wherein the slots extend only partially through the coverlay.

14. (Withdrawn) The integrated lead flexure of claim 11 wherein the slots extend through the coverlay.

15. (Original) The integrated lead flexure of claim 11 wherein the slots have a constant depth.

16. (Original) The integrated lead flexure of claim 11 wherein the slots have a constant pitch.

17. (Original) The integrated lead flexure of claim 11 wherein the slots are generally parallel to one another.

18. (Original) An integrated lead flexure, including:

a stainless steel layer;

a plurality of elongated electrical traces over the stainless steel layer;

a dielectric insulating layer between the stainless steel layer and the electrical traces;

a dielectric coverlay over at least portions of the traces; and

slots in at least portions of the coverlay oriented non-parallel to a longitudinal axis of the traces.

19. (Withdrawn) The integrated lead flexure of claim 18 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.

20. (Original) The integrated lead flexure of claim 18 wherein the slots extend only partially through the coverlay.

21. (Withdrawn) The integrated lead flexure of claim 18 wherein the slots extend through the coverlay.

22. (Original) The integrated lead flexure of claim 18 wherein the slots have a constant depth.

23. (Original) The integrated lead flexure of claim 18 wherein the slots have a constant pitch.

24. (Original) The integrated lead flexure of claim 18 wherein the slots are generally parallel to one another.

25. (Withdrawn) The integrated lead flexure of claim 24 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.

26. (New) A method of manufacturing an integrated lead suspension component, the method comprising:

applying a curable dielectric coverlay over at least a portion of an electrical trace;

forming slots oriented non-parallel to a longitudinal axis of the trace in at least a portion of the curable coverlay; and

curing the coverlay.

27. (New) The method of claim 26 wherein forming slots comprises forming slots in a generally perpendicular orientation to the longitudinal axis.

28. (New) The method of claim 26 wherein forming slots comprises forming slots with a constant depth.

29. (New) The method of claim 26 wherein forming slots comprises forming slots generally parallel to one another.

30. (New) The method of claim 26 wherein forming slots comprises forming slots with a constant pitch.

31. (New) The method of claim 26 wherein forming slots comprises forming slots with a pitch between approximately 25 and 200 μm.

32. (New) The method of claim 26 wherein forming slots comprises forming slots with a pitch of approximately 100 μm.

33. (New) The method of claim 26 wherein forming slots comprises forming slots extending only partially through the coverlay.

34. (New) The method of claim 26 wherein the integrated lead suspension includes a base layer and the method further comprises forming the electrical trace on the base layer.